



## Product Change Notification / LIAL-23USLU235

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**Date:**

13-Feb-2021

**Product Category:**

8-bit Microcontrollers, Interface- Controller Area Network (CAN), Interface- Serial Peripherals

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 3979 and 3979.001 Final Notice: Qualification of QMI-519 die attach material for selected products available in 28L SOIC (.300in) and 18L SOIC (.300in) packages at MTAI assembly site.

**Affected CPNs:**

[LIAL-23USLU235\\_Affected\\_CPN\\_02132021.pdf](#)  
[LIAL-23USLU235\\_Affected\\_CPN\\_02132021.csv](#)

**Notification Text:**

**PCN Status:** Final notification.

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the attachments found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .csv).

**Description of Change:** Qualification of QMI-519 die attach material for selected products available in 28L SOIC (.300in) and 18L SOIC (.300in) packages at MTAI assembly site.

**Pre Change:**

Using 3280 die attach material

**Post Change:**

Using QMI-519 die attach material

### Pre and Post Change Summary:

|                           | Pre Change                       | Post Change                      |
|---------------------------|----------------------------------|----------------------------------|
| Assembly Site             | Microchip Technology<br>Thailand | Microchip Technology<br>Thailand |
|                           | (MTAI)                           | (MTAI)                           |
| Wire material             | CuPdAu                           | CuPdAu                           |
| Die attach material       | 3280                             | QMI-519                          |
| Molding compound material | G600                             | G600                             |
| Lead frame material       | C194                             | C194                             |

**Impacts to Data Sheet:** None

**Change Impact:**None

**Reason for Change:**To improve productivity by qualifying QMI-519 die attach material

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**February 28, 2021 (date code: 2110)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

### Time Table Summary:

[illegible]

**Method to Identify Change:** Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:** **October 12, 2020:** Issued initial notification.

**February 13, 2021:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 28, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

[PCN\\_LIAL-23USLU235\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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